



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-08-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDK7*3079AF6	A	BO2A	2017-08-23
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MDF valid for MC33079DT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CDK7*3079AF6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	4.205	mg	supplier	die	Silicon (Si)	7440-21-3		4.109	mg	977170	31608	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.034	mg	8086	262	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4281	138	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.022	mg	5232	169	
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.022	mg	5232	169	
Leadframe	Copper & its alloys	37.978	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.870	mg	918163	268231	
				supplier	alloy	Iron (Fe)	7439-89-6		0.820	mg	21591	6308	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.049	mg	1290	377	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.043	mg	1132	331	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.460	mg	12112	3538	
				supplier	metallization	Palladium (Pd)	7440-05-3		0.029	mg	764	223	
				supplier	metallization	Gold (Au)	7440-57-5		0.012	mg	316	92	
				supplier	metallization	Silver (Ag)	7440-22-4		1.695	mg	44631	13038	
Die attach	Other inorganic materials	1.458	mg	supplier	glue	Silver (Ag)	7440-22-4		1.325	mg	908779	10192	
				supplier	glue	acrylate	Proprietary		0.073	mg	50069	562	
				supplier	glue	Methacrylate	Proprietary		0.058	mg	39781	446	
				supplier	glue	acrylate	Proprietary		0.001	mg	686	8	
				SVHC	glue	NMP	872-50-4		0.001	mg	686	8	
Bonding wires	Other inorganic materials	0.127	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	977	
Encapsulation	Other Organic Materials	85.332	mg	supplier	mold compound	Silica, vitreous	60676-86-0		73.898	mg	866006	568446	
				supplier	mold compound	Epoxy Resin	29690-82-2		6.400	mg	75001	49231	
				supplier	mold compound	Phenol Resin	25068-38-6		4.266	mg	49993	32815	
				supplier	mold compound	Carbon black	1333-86-4		0.427	mg	5004	3285	
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.341	mg	3996	2623	
connections coating	Solder	0.900	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.900	mg	1000000	6923	